L Number	Hits	Search Text	DB	Time stamp
1	44	(US-5694740-\$ or US-5644169-\$ or US-5615052-\$ or US-5600541-\$ or US-5610431-\$ or US-5579207-\$ or US-5532513-\$ or US-5549870-\$ or US-5222014-\$ or US-5247423-\$ or	USPAT; US-PGPUB	2002/07/17 15:11
2	17	US-5430421-\$ or US-4965660-\$ or US-4729010-\$ or US-6262362-\$ or US-6064126-\$ or US-5880403-\$ or US-5821762-\$ or US-6369448-\$ or US-6342406-\$ or US-6313522-\$ or US-6323550-\$ or US-6340894-\$ or US-6274929-\$ or US-6274927-\$).did. or US-6225692-\$ or US-6274927-\$).did. or (US-6185180-\$ or US-6188127-\$ or US-6143588-\$ or US-6214644-\$ or US-6143588-\$ or US-6214644-\$ or US-6163061-\$ or US-6025767-\$ or US-6163061-\$ or US-6025767-\$ or US-6101100-\$ or US-5962810-\$ or US-5790384-\$ or US-5936843-\$ or US-5790384-\$ or US-5936843-\$ or US-5783870-\$ or US-5730922-\$).did. or (US-20010026010-\$).did. ("4801998" "5222014" "5231036" "5578525" "5579207" "5786589"	USPAT	2002/07/17 15:30
3	16	"5821532" "5867368" "5907151" "5962810" "5973337" "6046070" "6122009" "6143981" "6144507" "6247229" "6281568").PN. ("5012323" "5121293" "5128831"	USPAT	2002/07/17
3		"5189505" "5289337" "5291061" "5323060" "5385869" "5422435" "5434745" "5474957" "5495398" "5513076" "5607099" "5963430" "6020629").PN.	USPAT	2002/07/17
4	2	6313522.URPN.	USPAT	2002/07/17 15:34
6	9	("4769344" "5296408" "5317922" "5335550" "5430421" "5602385" "5610431" "5929728" "6124145").PN. 6297072.URPN.	USPAT	2002/07/17 15:35 2002/07/17
7	26		USPAT	15:36 2002/07/17 15:37
11	4	("5610431" "5719069" "5915168" "6074891").PN.	USPAT	2002/07/17 15:39
12	0	6214644.URPN.	USPAT	2002/07/17 15:40
13	20	6025767.URPN. ("0557132" "3244947" "3259814" "3274458" "3316465" "3489965" "3916080" "3959577" "3993123" "4168480" "4257905" "4449580" "4511873" "4563697" "4565901" "4897508" "5046161" "5325265" "5475280" "5627396").PN.	USPAT	2002/07/17 15:41 2002/07/17 15:42
21	8	5610431.URPN.	USPAT	2002/07/17
22	0	6373130.URPN.	USPAT	2002/07/17

23		/W. F. T. O. C. O. H. H. C. C. C. C.		
23	2	("5578869" "5610431").PN.	USPAT	2002/07/17
24	28	/#A5 40070# #A600606# #A50060		15:46
24	28	1 1711215	USPAT	2002/07/17
		"4744863" "4764244" "4853669"		15:47
		"4855544" "4861420" "4874499"	1	
		"4904978" "4996082" "4996627"		
		"5013396" "5075253" "5101669"		
		"5165289" "5207103" "5233871" "5233874" "5264075" "5295395"		
		"5296408" "5318652" "5323051" "5324683" "5326726" "5335544"	1	
		"5343064").PN.		
_	162		TICDAM.	2000 (02 (25
	1 202	cap) with (spacer bead))	USPAT; US-PGPUB;	2002/03/25
		Tap, mean (spacer sead)	EPO; JPO;	07:09
			DERWENT	
-	149	((micromachine microelectronic) and ((lid	USPAT;	2001/11/27
		cap) with (spacer bead))) and substrate	US-PGPUB;	08:01
		,,,	EPO; JPO;	00.01
			DERWENT	
_	9	(((micromachine microelectronic) and	USPAT;	2001/11/26
		((lid cap) with (spacer bead))) and	US-PGPUB;	09:27
		substrate) and ((bond bonding) adj pad)	EPO; JPO;	
			DERWENT	
-	140		USPAT;	2001/11/26
		((lid cap) with (spacer bead))) and	US-PGPUB;	10:11
		substrate) not (((micromachine	EPO; JPO;	
		microelectronic) and ((lid cap) with	DERWENT	
	1	(spacer bead))) and substrate) and ((bond		
	_	bonding) adj pad))		
-	7	(((time of time of the of	USPAT;	2001/11/26
		((lid cap) with (spacer bead))) and	US-PGPUB;	10:25
	i	substrate) not (((micromachine	EPO; JPO;	
		microelectronic) and ((lid cap) with	DERWENT	
}		(spacer bead))) and substrate) and ((bond bonding) adj pad))) and package		
_	0		TIGDAM.	2001/11/25
		3397097.pm. and micromachine	USPAT; US-PGPUB;	2001/11/26
			EPO; JPO;	10:26
			DERWENT	
_	0	5397897.pn. and microelectronic	USPAT;	2001/11/26
			US-PGPUB;	10:27
			EPO; JPO;	10.2.
			DERWENT	
-	3	(micromachine microelectronic) and ((lid	USPAT;	2001/11/26
		cap) with dam)	US-PGPUB;	10:47
			EPO; JPO;	
			DERWENT	
-	116	257/619	USPAT;	2001/11/26
			US-PGPUB;	13:58
	[EPO; JPO;	
_	516	257/620	DERWENT	0001 (11 (0 1
_	210	237/620	USPAT;	2001/11/26
			US-PGPUB;	13:58
			EPO; JPO; DERWENT	
_	410	257/621	USPAT;	2001/11/26
1		, 	US-PGPUB;	13:58
1			EPO; JPO;	10.00
		İ	DERWENT	
-	1006	257/619 257/620 257/621	USPAT;	2001/11/26
			US-PGPUB;	13:59
			EPO; JPO;	
			DERWENT	
-	89	(257/619 257/620 257/621) and (lid cap	USPAT;	2001/11/26
		cover) and ((bond bonding)adj pad)	US-PGPUB;	14:03
			EPO; JPO;	
			DERWENT	

j -	396	, ,	USPAT;	2001/11/27
		microelectronic) near1 (device package))	US-PGPUB;	08:04
		and (lid cap) and substrate	EPO; JPO;	1
			DERWENT	1
_	41	((micromachine micromachined) near1	USPAT;	2001/11/27
	1	(device package)) and (lid cap) and	1	08:04
			US-PGPUB;	08:04
		substrate	EPO; JPO;	
			DERWENT	
-	10941	silicon near2 ceramic	USPAT;	2001/11/27
			US-PGPUB;	14:06
			EPO; JPO;	
			DERWENT	
_	2701	(silicon near2 ceramic) and (cap lid	USPAT;	2001/11/27
	2,01	cover)	US-PGPUB;	14:07
		COVELY		14:07
	1		EPO; JPO;	
ł	1		DERWENT	
i -	134	silicon near2 ceramic) with(cap lid cover	USPAT;	2001/11/27
			US-PGPUB;	14:07
			EPO; JPO;	
	}		DERWENT	
-	53	((silicon near2 ceramic) with (cap lid	USPAT;	2001/11/27
		cover)) and (semiconductor micromachined	1	14:08
1			US-PGPUB;	14:00
		micromachine)	EPO; JPO;	
			DERWENT]
-	51909		USPAT;	2002/03/25
1		microelectronic)	US-PGPUB;	07:10
			EPO; JPO;	
			DERWENT	
i _	54209	(micromachine micromachined	USPAT;	2002/04/12
	0.203	micromechanical micromirror	US-PGPUB;	07:18
		microelectronic)		07:10
		microelectronic)	EPO; JPO;	
			DERWENT	
-	165	1 , ,	USPAT;	2002/03/25
i		micromechanical micromirror	US-PGPUB;	07:19
		microelectronic)) and ((block blocking)	EPO; JPO;	
		near (adhesive material))	DERWENT	
_	2		USPAT;	2002/03/25
	_	327.3327	US-PGPUB;	08:10
			EPO; JPO;	00.10
		"5962810"	DERWENT	0000 (00 (05
-	8	"5962810"	USPAT;	2002/03/25
			US-PGPUB;	07:19
			EPO; JPO;	
			DERWENT	
-	9	"6274927" "5962810"	USPAT;	2002/03/25
			US-PGPUB;	07:19
1			EPO; JPO;	}
1			DERWENT	[
	5	5962810.URPN.	USPAT	2002/03/25
		050001010111111111111111111111111111111	201111	07:23
	, ,	 /#4E201E2# #4640418# #460122E#	HCDAM	
-	19	("4530152" "4649418" "4691225"	USPAT	2002/03/25
	į	"4801998" "4814943" "4890383"		07:24
		"5043004" "5068713" "5102829"		
	İ	"5126818" "5192681" "5241133"		
1		"5250470" "5336931" "5428188"		
		"5436203" "5474957" "5578525"		
		"5593926").PN.		
l _	23	("4530152" "4649418" "4691225"	USPAT	2002/03/25
	23	"4801998" "4890383" "5043004"		07:26
		· · · · · · · · · · · · · · · · · · ·		07.20
]		"5102829" "5126818" "5192681"		
]		"5241133" "5250470" "5336931"		
		"5436203" "5474957" "5530278"		1
		"5578525" "5593926" "5612513"		
		"5776798" "5861680" "5866953"		į l
		"5893723" "5918113").PN.		
-	ol	6274927.URPN.	USPAT	2002/03/25
				07:29
i				

	30	/#2020004# #4601005# #4001000#		10000 /00 /05
-	38	("3838984" "4691225" "4801998"	USPAT	2002/03/25
1		"5057905" "5070041" "5117279"		07:29
	1	"5122862" "5159432" "5230759"		1
		"5256901" "5258094" "5336931"		<u> </u>
		"5435057" "5436203" "5497032"		
1		"5529959" "5644169" "5656857"		
		"5776798" "5859471" "5861680"		
]		"5866953" "5867368" "5877043"		
		"5877546" "5893723" "5895222"		
		"5905301" "5949655" "5950074"		•
		"5962810" "5972738" "5981314"		
		"5989941" "5998862" "6034429"		
	7683		******	0000 (00 (05
_	/603	(micromachine micromachined	USPAT;	2002/03/25
		micromechanical (micromirror adj device))	US-PGPUB;	08:00
İ			EPO; JPO;	
			DERWENT	
-	1427	((micromachine micromachined	USPAT;	2002/03/25
		micromechanical (micromirror adj device))	US-PGPUB;	07:40
) and substrate and (wire wiring)	EPO; JPO;	
			DERWENT	
-	661	(((micromachine micromachined	USPAT;	2002/03/25
1		micromechanical (micromirror adj device))	US-PGPUB;	07:45
) and substrate and (wire wiring)) and	EPO; JPO;	
		(adhesive (sealing adj resin) encapsulant	DERWENT	
		encapsulated encapsualation)	~11/11/11/1	
_	655		USPAT;	2002/03/25
	655		•	
		micromechanical (micromirror adj device))	US-PGPUB;	07:46
) and substrate and (wire wiring)) and	EPO; JPO;	
		(adhesive (sealing adj resin) encapsulant	DERWENT	
		encapsulated encapsualation)) not		
		(((micromachine micromachined		
		micromechanical micromirror		
		microelectronic)) and ((block blocking)		l
		near (adhesive material)))		
_	486	((((micromachine micromachined	USPAT;	2002/03/25
		micromechanical (micromirror adj device))	US-PGPUB;	07:46
) and substrate and (wire wiring)) and	EPO; JPO;	
		(adhesive (sealing adj resin) encapsulant	DERWENT	
		encapsulated encapsualation)) not		
		(((micromachine micromachined		
		micromechanical micromirror		
		microelectronic)) and ((block blocking)		
		near (adhesive material)))) and wafer		
_	38	((((((micromachine micromachined	USPAT;	2002/03/25
-	30			07:54
		micromechanical (micromirror adj device))	US-PGPUB;	07.54
) and substrate and (wire wiring)) and	EPO; JPO;	
		(adhesive (sealing adj resin) encapsulant	DERWENT	
		encapsulated encapsualation)) not		
		(((micromachine micromachined		
		micromechanical micromirror		
		microelectronic)) and ((block blocking)		
		near (adhesive material)))) and wafer)		
		and curable		
-	0	20020031847.URPN.	USPAT	2002/03/25
				07:49
_	48	((((micromachine micromachined	USPAT;	2002/03/25
		micromechanical (micromirror adj device))	US-PGPUB;	07:54
) and substrate and (wire wiring)) and	EPO; JPO;	
		(adhesive (sealing adj resin) encapsulant	DERWENT	
	ı	encapsulated encapsualation)) not		
		(((micromachine micromachined		
		(((micromachine micromachined micromechanical micromirror		
		(((micromachine micromachined		

	10	1,,,,,		
-	10		USPAT;	2002/03/25
		micromechanical (micromirror adj device))	US-PGPUB;	07:55
İ) and substrate and (wire wiring)) and	EPO; JPO;	
		(adhesive (sealing adj resin) encapsulant	DERWENT	İ
		encapsulated encapsualation)) not		
		(((micromachine micromachined		
		micromechanical micromirror	İ	
		microelectronic)) and ((block blocking)		İ
		microelectionic) and (block blocking)		
ŀ		near (adhesive material)))) and curable)		
		not ((((((micromachine micromachined		
		micromechanical (micromirror adj device))	İ	
) and substrate and (wire wiring)) and		
		(adhesive (sealing adj resin) encapsulant		
		encapsulated encapsualation)) not	1	
		(((micromachine micromachined		
		micromechanical micromirror		
		· · · · · · · · · · · · · · · · · · ·		Į.
		microelectronic)) and ((block blocking)		
		near (adhesive material)))) and wafer)		
		and curable)		
-	18	(micromachine micromachined	USPAT;	2002/03/25
		micromechanical (micromirror adj device))	US-PGPUB;	08:05
1		near3 (ccd (charge adj coupled adj	EPO; JPO;	33.33
	1	device) (surface adj acoustical adj	DERWENT	1
	1	wave))	DELMENT	
_				1 0000 405 455
-	1	6274927.pn. and curable	USPAT;	2002/03/25
			US-PGPUB;	08:11
			EPO; JPO;	
			DERWENT	
-	0	6143588.pn. and curable	USPAT;	2002/03/25
			US-PGPUB;	08:12
İ	1			00:12
			EPO; JPO;	
		C117705	DERWENT	
-	0	6117705.pn. and curable	USPAT;	2002/03/25
			US-PGPUB;	10:20
			EPO; JPO;	
			DERWENT	
_	0	5866953.pn. and curable	USPAT;	2002/03/25
			US-PGPUB;	08:16
			EPO; JPO;	08.16
				l i
	_	F.C1F.0F.0	DERWENT	1
-	3	5615052.pn.	USPAT;	2002/03/25
			US-PGPUB;	08:16
			EPO; JPO;	
1			DERWENT	1
-	2	6185180.pn.	USPAT;	2002/03/25
		•	US-PGPUB;	08:16
	į į		EPO; JPO;	00.10
]	İ		į l
	-	6105100 mm	DERWENT	0000 (00 (5-
-	5	6185180.pn. 5615052.pn.	USPAT;	2002/03/25
			US-PGPUB;	08:16
			EPO; JPO;	
			DERWENT	
-	2	6117705.pn. and ("300" "310" "320" "325"	USPAT;	2002/03/25
	-	"329")	US-PGPUB;	13:48
		/	EPO; JPO;	13.10
			· ·	
		/h11	DERWENT	0000 (00 (==
-	0	(hysol silicone) near3 stacky	USPAT;	2002/03/25
			US-PGPUB;	14:07
			EPO; JPO;	
			DERWENT	1
-	377	(hysol silicone) near3 tacky	USPAT;	2002/03/25
	"'		US-PGPUB;	13:55
				13:33
	1		EPO; JPO;	
1			DERWENT	
-	0	((hysol silicone) near3 tacky) with	USPAT;	2002/03/25
	1	(gettering getter)	US-PGPUB;	13:51
1			EPO; JPO;	
	1		DERWENT	
				

-	0	(() 1 and	USPAT;	2002/03/25
1		(gettering getter)	US-PGPUB;	13:51
			EPO; JPO;	
			DERWENT	
-	33	((hysol silicone) near3 tacky) and micro	USPAT;	2002/03/25
			US-PGPUB;	13:54
			EPO; JPO;	120.01
			DERWENT	
-	86	((hysol silicone) near3 tacky) and	USPAT;	2002/03/25
		(semiconductor IC electronic chip die)	US-PGPUB;	13:54
		(someonadotor to creestonic chip die)	EPO; JPO;	13.54
_	1	///hygol giligonol mongo to alan) and	DERWENT	0000 (00 (05
	1		USPAT;	2002/03/25
		(semiconductor IC electronic chip die))	US-PGPUB;	13:55
		and hysol	EPO; JPO;	
			DERWENT	
-	1	adhesive near3 stacky	USPAT;	2002/03/25
i			US-PGPUB;	14:07
			EPO; JPO;	
			DERWENT	
-	54209		USPAT;	2002/03/25
		micromechanical micromirror	US-PGPUB;	14:25
		microelectronic	EPO; JPO;	1 2 3 3 2 3
			DERWENT	
-	14411	(micromachine micromachined	USPAT;	2002/03/25
		micromechanical micromirror	1	
		microelectronic) and etching	US-PGPUB;	14:26
		microerectionic) and eccuring	EPO; JPO;	
	,	/md mama abd no md masses abd no 3	DERWENT	0000 (5- /
-	1	(micromachine micromachined	USPAT;	2002/03/25
		micromechanical micromirror	US-PGPUB;	14:29
		microelectronic) and (etching near3	EPO; JPO;	
		(active adj surface))	DERWENT	i
-	1	(micromachine micromachined	USPAT;	2002/03/25
		micromechanical micromirror	US-PGPUB;	14:30
		microelectronic) and (etching near5	EPO; JPO;	
		(active adj surface))	DERWENT	
-	19	(micromachine micromachined	USPAT;	2002/03/25
		micromechanical micromirror	US-PGPUB;	14:34
		microelectronic) and (etching with	EPO; JPO;	111.54
		(active adj surface))	DERWENT	
	82	(micromachine micromachined	_	2002/02/05
	02	micromachine micromachined	USPAT;	2002/03/25
			US-PGPUB;	14:36
		microelectronic) and (etching with (resin	EPO; JPO;	
		adhesive encapsulant) with surface)	DERWENT	1 (
-	81	((micromachine micromachined	USPAT;	2002/03/25
		micromechanical micromirror	US-PGPUB;	14:37
		microelectronic) and (etching with (resin		
	[adhesive encapsulant) with surface)) not	DERWENT	
]	((micromachine micromachined		
		micromechanical micromirror		
]	microelectronic) and (etching with		
		(active adj surface)))		
l -	4678	(micromachine micromachined)	USPAT;	2002/04/12
			US-PGPUB;	07:00
]		EPO; JPO;	0,.00
1			•	
			DERWENT	2002/04/20
-	346	((micromachine micromachined)) and (cap	USPAT;	2002/04/12
		lid) and substrate	US-PGPUB;	07:18
			EPO; JPO;	
			DERWENT	1
-	37	(((micromachine micromachined)) and (cap	USPAT;	2002/04/12
	Į l	lid) and substrate) and (bump flipchip	US-PGPUB;	07:19
	[(flip adj chip) ((solder conductive	EPO; JPO;	
		metal) adj ball))	DERWENT	
-	7	("5369057" "5585675" "5663596"	USPAT	2002/04/12
		"5721162" "5831162" "5907187"		07:08
		"6087203").PN.	į	
_	1 1	6225692.URPN.	USPAT	2002/04/12
				07:09
_	4	("5610431" "5719069" "5915168"	USPAT	2002/04/12
1	"	"6074891").PN.	ODIAL	07:10
L	l	OUITODI J.EN.		07.10

-	6	5610431.URPN.	USPAT	2002/04/12
1	0	6297072.URPN.	HCDAM	07:11 2002/04/12
-	0	6297072.URPN.	USPAT	07:12
-	9		USPAT	2002/04/12
		"5335550" "5430421" "5602385"		07:12
_	28	"5610431" "5929728" "6124145").PN. ("4548078" "4680606" "4744249"	USPAT	2002/04/12
	20	"4744863" "4764244" "4853669"	OSTA	07:15
		"4855544" "4861420" "4874499"		
		"4904978" "4996082" "4996627" "5013396" "5075253" "5101669"		
		"5165289" "5207103" "5233871"		
		"5233874" "5264075" "5295395"		
		"5296408" "5318652" "5323051" "5324683" "5326726" "5335544"		
		"5343064").PN.		
-	0	6214644.URPN.	USPAT	2002/04/12
_	54707	micromachine micromachined	USPAT;	07:17
		micromechanical micromirror	US-PGPUB;	07:18
		microelectronic	EPO; JPO;	
i_	252	((micromachine micromachined	DERWENT USPAT;	2002/04/12
		micromechanical micromirror	US-PGPUB;	07:34
		microelectronic) and (cap lid) and	EPO; JPO;	
		substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum	DERWENT	
		ball)))		
-	234	1 ' ' '	USPAT;	2002/04/12
		micromechanical micromirror microelectronic) and (cap lid) and	US-PGPUB; EPO; JPO;	07:20
		substrate) and (flipchip (flip adj chip)	DERWENT	
		((solder conductive metal) adj (bum		
		ball)))) not ((((micromachine micromachined)) and (cap lid) and		
		substrate) and (bump flipchip (flip adj		
		chip) ((solder conductive metal) adj		
_	0	((((micromachine micromachined	USPAT;	2002/04/12
	_	micromechanical micromirror	US-PGPUB;	07:36
		microelectronic) and (cap lid) and substrate) and (flipchip (flip adj chip)	EPO; JPO; DERWENT	
		((solder conductive metal) adj (bum	DERWENT	
		ball)))) not ((((micromachine		
		micromachined)) and (cap lid) and substrate) and (bump flipchip (flip adj	}	
		chip) ((solder conductive metal) adj		
		ball)))) and ((electro magnetic) near2		
	24	shield) (((micromachine micromachined	USPAT;	2002/04/12
_	24	micromechanical micromirror	US-PGPUB;	07:36
		microelectronic) and (cap lid) and	EPO; JPO;	
		substrate) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum	DERWENT	
		ball)))) not (((micromachine		
		micromachined)) and (cap lid) and		
		substrate) and (bump flipchip (flip adj chip) ((solder conductive metal) adj		
		ball)))) and shield		
-	240	(micromachine micromachined	USPAT;	2002/04/12
		micromechanical micromirror microelectronic) and ((insulating	US-PGPUB; EPO; JPO;	07:27
		insulative dielectric insulation) near3	DERWENT	
		(cap lid))		

-	240	, ,	USPAT;	2002/04/12
		micromechanical micromirror	US-PGPUB;	07:27
		microelectronic) and ((insulating	EPO; JPO;	
		insulative dielectric insulation) near3	DERWENT	
Ì		(cap lid))) not (((micromachine		
		micromachined)) and (cap lid) and		
		substrate) and (bump flipchip (flip adj		
		chip) ((solder conductive metal) adj		
	1	(ball)))		
-	1	(((micromachine micromachined micromechanical micromirror	USPAT;	2002/04/12
			US-PGPUB;	07:30
		microelectronic) and ((insulating	EPO; JPO;	
		insulative dielectric insulation) near3	DERWENT	
		(cap lid))) not (((micromachine		
		micromachined)) and (cap lid) and		
		substrate) and (bump flipchip (flip adj		
		chip) ((solder conductive metal) adj		
		ball)))) and ((cap lid) near3 ((bond		
		bonding metal conductive) near pad))		
-	2		USPAT;	2002/04/12
		micromechanical micromirror	US-PGPUB;	07:29
		microelectronic) and ((insulating	EPO; JPO;	
1		insulative dielectric insulation) near3	DERWENT	
1	1	(cap lid))) not (((micromachine		
		micromachined)) and (cap lid) and		
	1	substrate) and (bump flipchip (flip adj	1	
		chip) ((solder conductive metal) adj		
		ball)))) and ((cap lid) with ((bond		
		bonding metal conductive) near pad))		
-	16	, , ,	USPAT;	2002/04/12
		micromechanical micromirror	US-PGPUB;	07:36
		microelectronic) and ((insulating	EPO; JPO;	
		insulative dielectric insulation) near3	DERWENT	
		(cap lid))) not (((micromachine		
		micromachined)) and (cap lid) and		
		substrate) and (bump flipchip (flip adj		
i		chip) ((solder conductive metal) adj	}	
		ball)))) and ((bond bonding metal		
		conductive) near pad)		
-	30962	semiconductor near2 (package packaging)	USPAT;	2002/04/12
			US-PGPUB;	07:33
			EPO; JPO;	
			DERWENT	
-	3754	(semiconductor near2 (package packaging))	USPAT;	2002/04/12
		and (flipchip (flip adj chip) ((solder	US-PGPUB;	07:34
		conductive metal) adj (bum ball)))	EPO; JPO;	
			DERWENT	
_	1615	((semiconductor near2 (package	USPAT;	2002/04/12
		packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:42
	1	((solder conductive metal) adj (bum	EPO; JPO;	
		ball)))) and (cap lid cover) and (base	DERWENT	
	1	substrate)		
-	930	(((semiconductor near2 (package	USPAT;	2002/04/12
		packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:36
		((solder conductive metal) adj (bum	EPO; JPO;	
		ball)))) and (cap lid cover) and (base	DERWENT	
	1	substrate)) and ((bond bonding metal		
		conductive) near pad)		
_	3	((((semiconductor near2 (package	USPAT;	2002/04/12
		packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:36
	1	((solder conductive metal) adj (bum	EPO; JPO;	
	1	ball)))) and (cap lid cover) and (base	DERWENT	
		substrate)) and ((bond bonding metal		
	1	conductive) near pad)) and ((electro		
		magnetic) near2 shield)		
_	50	((((semiconductor near2 (package	USPAT;	2002/04/12
		packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:37
		((solder conductive metal) adj (bum	EPO; JPO;	
	 	ball)))) and (cap lid cover) and (base	DERWENT	
		substrate)) and ((bond bonding metal		
		conductive) near pad)) and shield		
	 			

	1 2 2 5			
-	195	((semiconductor near2 (package	USPAT;	2002/04/12
1		packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:53
		((solder conductive metal) adj (bum	EPO; JPO;	
		ball)))) and ((cap lid cover) with	DERWENT	
	101	((through adj hole) vias))		
_	181	(((semiconductor near2 (package	USPAT;	2002/04/12
		packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:43
		((solder conductive metal) adj (bum	EPO; JPO;	
		ball)))) and ((cap lid cover) with	DERWENT	
		((through adj hole) vias))) not		
		((((semiconductor near2 (package		
		packaging)) and (flipchip (flip adj chip)		
		((solder conductive metal) adj (bum		
		ball)))) and (cap lid cover) and (base		
		substrate)) and ((bond bonding metal		
	276070	conductive) near pad)) and shield)		
_	376878	((((semiconductor near2 (package	USPAT;	2002/04/12
		packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:43
	1	((solder conductive metal) adj (bum	EPO; JPO;	
		ball)))) and ((cap lid cover) with	DERWENT	
	!	((through adj hole) vias))) not		
		(((((semiconductor near2 (package	1	Į
		packaging)) and (flipchip (flip adj chip)		}
		((solder conductive metal) adj (bum		
		ball)))) and (cap lid cover) and (base		
1		substrate)) and ((bond bonding metal	1	
		conductive) near pad)) and shield))		
	44	(stack stacked) ((((semiconductor near2 (package	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	2000/04/10
-	44		USPAT;	2002/04/12
1		packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:55
		((solder conductive metal) adj (bum	EPO; JPO;	
		ball)))) and ((cap lid cover) with ((through adj hole) vias))) not	DERWENT	
		(((((semiconductor near2 (package		
		packaging)) and (flipchip (flip adj chip)		
		((solder conductive metal) adj (bum		
		ball)))) and (cap lid cover) and (base		
		substrate)) and ((bond bonding metal	· ·	
		conductive) near pad)) and shield)) and		
		(stack stacked)		
_	1278	((semiconductor near2 (package	USPAT;	2002/04/12
	****	packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:54
		((solder conductive metal) adj (bum	EPO; JPO;	- / • • •
		ball)))) and ((cap lid cover)	DERWENT	
		and((through adj hole) vias))		
_	1054	(((semiconductor near2 (package	USPAT;	2002/04/12
		packaging)) and (flipchip (flip adj chip)	US-PGPUB;	07:55
		((solder conductive metal) adj (bum	EPO; JPO;	
		ball)))) and ((cap lid cover)	DERWENT	
		and((through adj hole) vias))) not		
		(((((semiconductor near2 (package		
		packaging)) and (flipchip (flip adj chip)		1
		((solder conductive metal) adj (bum		
		ball)))) and (cap lid cover) and (base		
		substrate)) and ((bond bonding metal		
		conductive) near pad)) and shield) not		
		(((semiconductor near2 (package		
		packaging)) and (flipchip (flip adj chip)		
		((solder conductive metal) adj (bum		
		ball)))) and ((cap lid cover) with		1
		((through adj hole) vias)))		
		Sungress of		

	1191	(((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) and((through adj hole) vias))) not ((((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield) not ((((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and ((cap lid cover) with ((through adj hole) vias))) not ((((semiconductor near2 (package packaging)) and (flipchip (flip adj chip) ((solder conductive metal) adj (bum ball)))) and (cap lid cover) and (base substrate)) and ((bond bonding metal conductive) near pad)) and shield)) and (stack stacked))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/12
-	0	6294406.URPN.	USPAT	2002/04/12
_	16	"5399898" "5401672" "5434453" "5446247" "5495394" "5541449" "5563773" "5576519" "5600541" "5760478" "5770480" "5790384"	USPAT	08:09 2002/04/12 08:09
_	20	"6069025").PN. 5600541.URPN.	USPAT	2002/04/12
-	7	6025648.URPN.	USPAT	08:11 2002/04/12 08:15
-	8	("5276289" "5798567" "5854507" "5869894" "5936843" "5969944" "5994166" "6025648").PN.	USPAT	2002/04/12 08:18
_	26	("3179913" "3370203" "3459998" "3904934" "4288841" "4502098" "4574331" "4646128" "4727410" "4823233" "4833568" "4862249" "4868712" "4953005" "5016138" "5019945" "5674785" "5854507" "5883426" "5973392" "6013948" "6020629" "6025648" "6072233" "6137164" "6188127").PN.	USPAT	2002/04/12 08:22
-	16	("4894706" "5016138" "5222014" "5247423" "5600541" "5633783" "5715144" "5742477" "5760478" "5786628" "5798562" "5801438" "5807986" "5811879" "5838060" "5838551").PN.	USPAT	2002/04/12 08:26
-	95	5222014.URPN.	USPAT	2002/04/12 08:30
-	24	5790384.URPN.	USPAT	2002/04/12
-	22	5783870.URPN.	USPAT	2002/04/12 09:10
_	36	("3436603" "4807021" "4867235" "4933810" "4953060" "4991000" "5060844" "5099309" "5128831" "5130894" "5172303" "5222014" "5241133" "5241450" "5241456" "5247423" "5299094" "5307240" "5313366" "5376825" "5391917" "5394010" "5394300" "5397917" "5412538" "5421081" "5422435" "5454160" "5579207" "5615089" "5633783" "5642265" "5739581" "5783870" "5798564" "5920117").PN.	USPAT	2002/04/12

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		US-4965660-\$ or US-4729010-\$ or		
		US-6342406-\$ or US-6274927-\$ or	1	
		US-6143588-\$ or US-5962810-\$ or		
		US-5866953-\$ or US-6117705-\$ or		
		US-5644169-\$ or US-6185180-\$ or		
	İ	US-5615052-\$ or US-5610431-\$ or		
	ł	US-5730922-\$ or US-5549870-\$ or		
		US-6297072-\$ or US-5430421-\$ or		
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		(US-6340894-\$ or US-6313522-\$ or		
		US-5790384-\$ or US-5600541-\$ or		
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		US-5222014-\$ or US-6101100-\$ or		
		US-5783870-\$ or US-5579207-\$).did. or		
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			:	
1		US-5866953-\$ or US-6117705-\$ or		1
		US-5644169-\$ or US-6185180-\$ or	Į	
		US-5615052-\$ or US-5610431-\$ or		
		US-5730922-\$ or US-5549870-\$ or		
		US-6297072-\$ or US-5430421-\$ or		
		US-6274929-\$ or US-6369448-\$).did. or	ļ	
		(US-6340894-\$ or US-6313522-\$ or		
		US-5790384-\$ or US-5600541-\$ or	İ	!
		US-6025648-\$ or US-5936843-\$ or		
		US-6188127-\$ or US-5247423-\$ or		
		US-5222014-\$ or US-6101100-\$ or		
		US-5783870-\$ or US-5579207-\$).did. or		
		(US-20010026010-\$ or		
		US-20010008794-\$).did.) and (emi (electro]
		near1 magnetic neaer1 shield))		
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		US-4965660-\$ or US-4729010-\$ or		
		US-6342406-\$ or US-6274927-\$ or		
	[US-6143588-\$ or US-5962810-\$ or		
		US-5866953-\$ or US-6117705-\$ or		į l
1		US-5644169-\$ or US-6185180-\$ or		
		US-5615052-\$ or US-5610431-\$ or		
		US-5730922-\$ or US-5549870-\$ or		
1		US-6297072-\$ or US-5430421-\$ or		j
		US-6274929-\$ or US-6369448-\$).did. or		
		(US-6340894-\$ or US-6313522-\$ or		
		US-5790384-\$ or US-5600541-\$ or]
		US-6025648-\$ or US-5936843-\$ or		
		US-6188127-\$ or US-5247423-\$ or		
		US-5222014-\$ or US-6101100-\$ or	•	
		US-5783870-\$ or US-5579207-\$).did. or		
		(US-20010026010-\$ or		
]		· ·		
		US-20010008794-\$).did.) and (emi]
L		(electromagnetic nearl shield))		L

		1 / / · · · · · · · · · · · · · · · · ·		
_	1	((US-6025767-\$ or US-6163061-\$ or	USPAT;	2002/04/15
		US-6323550-\$ or US-6225692-\$ or	US-PGPUB;	09:16
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		US-6342406-\$ or US-6274927-\$ or		
		US-6143588-\$ or US-5962810-\$ or		
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		US-5783870-\$ or US-5579207-\$).did. or		
		(US-20010026010-\$ or		1
		US-20010008794-\$).did.) and (emi		
		(electromagnetic near1 interference))		
_	2191	(micromachine micromachined	USPAT;	2002/04/15
		micromechanical micromirror	US-PGPUB;	09:16
		microelectronic) and (cap lid) and	EPO; JPO;	
	1	substrate	DERWENT	
_	108	((micromachine micromachined	USPAT;	2002/04/15
		micromechanical micromirror	US-PGPUB;	09:18
		microelectronic) and (cap lid) and	EPO; JPO;	03.20
		substrate) and (emi (electromagnetic	DERWENT	
		near1 (shield interference)) (electro adj		
	,	magnetic adj interference))]	
_	64		USPAT;	2002/04/15
		micromechanical micromirror	US-PGPUB;	09:18
		microelectronic) and (cap lid) and	EPO; JPO;	
		substrate) and ((electromagnetic near1	DERWENT	
		(shield interference)) (electro adj		
		magnetic adj interference))		
_	30	(((micromachine micromachined	USPAT;	2002/04/15
		micromechanical micromirror	US-PGPUB;	09:41
		microelectronic) and (cap lid) and	EPO; JPO;	
		substrate) and (emi (electromagnetic	DERWENT	
		near1 (shield interference)) (electro adj]
		magnetic adj interference))) and		
		(semiconductor near1 (device package		
		packaging))		
_	10	5639989.pn. 5578525.pn. 5981314.pn.	USPAT;	2002/04/15
	10	6150716.pn. 6308938.pn	US-PGPUB;	09:42
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			DERWENT	
			DEKMENT	